

Technical Data Sheet

Maywotron[®] ABS/TPU Vol-R

ABS / TPU

Typical characteristics

- Protection of electronic devices from electrostatic phenomena
- Conductive & dissipative

Typical industries

- Tecnica di imbutitura
- Elettronica
- Semiconductor Dicing

	Test method	Unit	Guideline value
General properties			
Density	DIN EN ISO 1183-1	g / cm ³	1,10
Water absorption	DIN EN ISO 62	%	0,3
Flammability (Thickness 1,5mm / 3 mm)	UL 94		HB
Mechanical properties			
Yield stress	DIN EN ISO 527	MPa	32
Elongation at break	DIN EN ISO 527	%	35
Tensile modulus of elasticity	DIN EN ISO 527	MPa	2125
Notched impact strength	DIN EN ISO 179	kJ / m ²	20
Rockwell hardness (ABS)	DIN EN ISO 2039-2	scale R	80
Thermal properties			
Melting temperature	ISO 11357-3	°C	>180°C
Thermal conductivity	DIN 52612-1	W / (m * K)	0,17
Coefficient of linear thermal expansion	DIN 53752	10 ⁻⁶ / K	90
Service temperature, long term	Average	°C	85
Service temperature, short term (max.)	Average	°C	100
Vicat softening temperature	DIN EN ISO 306, Vicat B	°C	102
Electrical properties			
Surface resistivity	DIN EN 61340	Ω	10 ⁴ - 10 ⁶
Volume resistivity	DIN EN 61340	Ω	10 ⁴ - 10 ⁶

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